

 GLAST LAT SUBSYSTEM SPECIFICATION	Document # <b>LAT-SS-02235-03</b>	Date Effective 28 Oct 2003
	Prepared by(s) J. Eric Grove Nick Virmani	Supersedes None
	Subsystem/Office Calorimeter Subsystem	
Document Title <b>CAL FM Crystal Detector Element Acceptance Test Plan</b>		

**Gamma-ray Large Area Space Telescope (GLAST)**  
**Large Area Telescope (LAT)**  
**Calorimeter Flight Model**  
**Crystal Detector Element Acceptance Test Plan**

## DOCUMENT APPROVAL

**Prepared by:**

\_\_\_\_\_  
J. Eric Grove  
CAL Subsystem Instrument Scientist

\_\_\_\_\_  
Date

\_\_\_\_\_  
Nick Virmani  
CAL Subsystem Quality Assurance Manager

\_\_\_\_\_  
Date

**Approved by:**

\_\_\_\_\_  
W. Neil Johnson  
CAL Subsystem Manager

\_\_\_\_\_  
Date

## CHANGE HISTORY LOG

<b>Revision</b>	<b>Effective Date</b>	<b>Description of Changes</b>
03	28 October 2003	Initial Release

**Hard copies of this document are for REFERENCE ONLY and should not be considered the latest revision.**

## Table of Contents

<b>1</b>	<b>INTRODUCTION.....</b>	<b>6</b>
1.1	PURPOSE.....	6
1.2	SCOPE.....	6
1.3	APPLICABLE DOCUMENTS .....	6
1.4	DEFINITIONS AND ACRONYMS .....	6
1.4.1	<i>Acronyms</i> .....	6
1.4.2	<i>Definitions</i> .....	6
<b>2</b>	<b>INTRODUCTION.....</b>	<b>8</b>
2.1	FM CDE Components.....	8
2.2	Traceability .....	8
<b>3</b>	<b>CDE ACCEPTANCE TESTS.....</b>	<b>10</b>
3.1	Visual Inspection .....	10
3.1.1	<i>Requirements</i> .....	10
3.1.2	<i>Test Location</i> .....	10
3.1.3	<i>Reporting</i> .....	11
3.2	Mechanical.....	11
3.2.1	<i>Requirements</i> .....	11
3.2.2	<i>Test Location</i> .....	11
3.2.3	<i>Reporting</i> .....	12
3.3	Optical.....	12
3.3.1	<i>Requirements</i> .....	12
3.3.2	<i>Test Location</i> .....	12
3.3.3	<i>Reporting</i> .....	12
3.4	Bond Strength .....	13
3.4.1	<i>Requirement</i> .....	13
3.4.2	<i>Test Location</i> .....	13
3.4.3	<i>Reporting</i> .....	13
3.5	Thermal stability .....	13
3.5.1	<i>Requirements</i> .....	13
3.5.2	<i>Test Location</i> .....	13
3.5.3	<i>Reporting</i> .....	13
<b>4</b>	<b>ACCEPTANCE DATA PACKAGE .....</b>	<b>14</b>
4.1	Reporting.....	14
4.1.1	<i>Contents of Tracking Spreadsheet</i> .....	14
4.1.2	<i>Contents of Optical Test Report</i> .....	14

4.2	Certificate of Conformance.....	15
-----	---------------------------------	----

### List of Figures

Figure 1: Crystal Detector Element assembly. Note that the CDE is depicted with its “top” surface – with the seam-sealing tape – down. The seal tape is therefore not shown. The CDE assembly drawing is LAT-DS-1900.....	8
---	---

### List of Tables

Table 3-1. Dimensional requirements for completed CDEs.....	11
Table 3-2. Optical performance requirements. ....	12
Table 4-1: Contents of CDE Tracking Spreadsheet.....	14
Table 4-2. Contents of CDE muon optical test report. ....	15

# 1 INTRODUCTION

## 1.1 PURPOSE

This document defines the acceptance test plan for Flight Model (FM) Calorimeter (CAL) Crystal Detector Elements (CDEs) assembled at Swales Aerospace. Elements of these acceptance tests will be performed at both Swales and NRL, as appropriate, as indicated herein.

## 1.2 SCOPE

We describe the complete set of tests to be performed on FM CDEs at Swales and NRL. These acceptance tests ensure that CDEs assembled at Swales meet the relevant requirements identified in the CAL FM Crystal Detector Element Specification (LAT-SS-01133).

## 1.3 APPLICABLE DOCUMENTS

The following documents are applicable to the extent specified within. Unless otherwise indicated, the latest issue in effect shall apply. In the event of a conflict between these documents and the contents of this document, those contained herein shall be considered the superseding requirement.

GE-00010	GLAST LAT Performance Specification
LAT-SS-00010	LAT Performance Specification – Level II (b) Specification
LAT-SS-00018	LAT CAL Subsystem Specification - Level III Specification
LAT-SS-00210	LAT CAL Subsystem Specification – Level IV Specification
LAT-SS-00601	LAT Calorimeter Structure to CDE Interface Control Document
LAT-TD-00381	LAT Calorimeter CDE Light Yield Calibration Procedure
LAT-PS-00809	LAT Calorimeter CsI Crystal Handling and Shipping Procedure
LAT-DS-00820	LAT Calorimeter CsI Crystal Performance Specification
LAT-DS-00209	LAT Calorimeter Flight Dual PIN Photodiode Specification
LAT-PS-01330	Calorimeter Flight Photodiode Assembly Soldering & Staking Process Specification
LAT-PS-01534	Calorimeter Flight Model Photodiode Assembly Specification
LAT-PS-01331	Calorimeter Flight Crystal to PDA Bonding Process Specification
LAT-PS-01332	Calorimeter Flight Crystal Wrapping and Capping Process Specification
LAT-SS-01133	Calorimeter Flight Crystal Detector Element Specification
LAT-DS-01900	Crystal Detector Element Assembly Drawing
LAT-MD-00228	Calorimeter, Tracker, and Data Acquisition Contamination Control Plan
LAT-PS-02571	CAL Crystal Detector Element Optical Test Procedure
LAT-PS-02572	Process Specification for the Bond Strength Testing of the CDE

## 1.4 DEFINITIONS AND ACRONYMS

### 1.4.1 Acronyms

CAL	Calorimeter Subsystem of the LAT
CDE	Crystal Detector Element
DPD	Dual PIN photoDiode
GLAST	Gamma-Ray Large Area Space Telescope
LAT	Large Area Telescope
NCR	Non-Conformance Report
PDA	PhotoDiode Assembly
TBD	To Be Determined
TBR	To Be Resolved

### 1.4.2 Definitions

Analysis	A quantitative evaluation of a complete system and/or subsystems by
----------	---

**Hard copies of this document are for REFERENCE ONLY and should not be considered the latest revision.**

	review/analysis of collected data
Demonstration	To prove or show, usually without measurements of instrumentation, that the project/product complies with requirements by observation of the results.
Inspection	To examine visually or use simple physical measurement techniques to verify conformance to specified requirements.
Simulation	To examine through model analysis or modeling techniques to verify conformance to specified requirements
Testing	A measurement to prove or show, usually with precision measurement or instrumentation, that the product complies with requirements.
Validation	Process used to assure the requirement set is complete and consistent, and that each requirement is achievable.
Verification	Process used to ensure that the selected solutions meet specified requirements and properly integrate with interfacing products
µm	micrometer
mm	millimeter

## 2 INTRODUCTION

### 2.1 FM CDE COMPONENTS

The Flight CDE assembly consists of the following components. These are depicted in Figure 1. The CDE assembly drawing is LAT-DS-01900.

- One FM CsI(Tl) scintillating crystal, which is a rectangular parallelepiped with a chamfer on the corners of the long dimension, as defined in LAT-DS-00820.
- Two FM Photodiode Assemblies (PDAs), one bonded to each end of the CsI crystal. As defined in LAT-PS-01534, each PDA consists of:
  - One Dual PIN photoDiode (DPD) as defined in LAT-DS-00209, and
  - Two sets of interconnect wire pairs attached to the leads of the DPD.
- Two optical bonds attaching the PDA assemblies, one to each CsI crystal end using a DC93-500 silicone optical adhesive in accordance with LAT-PS-01331.
- One VM2000 Optical Reflective Wrap sealed with acrylic-adhesive Kapton tape applied in accordance with LAT-PS-01332.
- Two Machined End Caps attached over bonded PDAs and optical reflective wrap at both ends of the crystal to close out the ends of the CDE in accordance with LAT-PS-01332.
- One label indicating crystal serial number and orientation as defined in the FM CDE Specification (LAT-SS-01133).

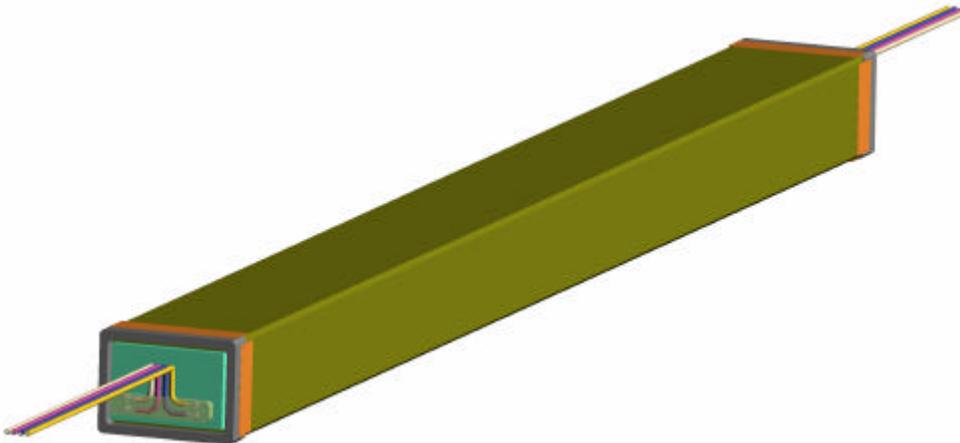


Figure 1: Crystal Detector Element assembly. Note that the CDE is depicted with its “top” surface – with the seam-sealing tape – down. The seal tape is therefore not shown. The CDE assembly drawing is LAT-DS-1900.

### 2.2 TRACEABILITY

The CsI(Tl) crystal and the photodiodes are individually serialized by the manufacturers in the manner indicated in their respective specification documents. Full traceability of these serial numbers shall be maintained throughout the entire process of CDE assembly.

The DC93-500 silicone encapsulant and DC92-023 primer are identified by batch numbers and subject to an expiration date. A single batch is a sufficient quantity to make many optical bonds. Batch number and expiration date shall be traceable for all flight CDEs.

The VM2000 wrapper is identified by the lot and roll number of its parent roll. One roll is sufficient to make hundreds of wrappers. No further identification of wrapper within its lot and roll need be given. Wrapper lot number and roll number shall be traceable for all flight CDEs.

The end caps are identified by lot number. One lot of end caps is sufficient for a few tens of CDEs. End cap lot number shall be traceable for all flight CDEs.

Each assembled CDE shall be serialized by its unique component crystal.

One "lot" of CDEs shall be comprised of the 12 CDEs assembled on a single bonding workstand segment. If fewer than 12 CDEs are bonded in a given session, only those CDEs that are bonded in a given session at a single workstand segment can be considered as a lot.

Full traceability of the serial numbers, batch numbers, and lot numbers specified above shall be maintained. The bonding and wrapping log shall document the serial, batch, and lot numbers of the components that comprise each assembled CDE.

### 3 CDE ACCEPTANCE TESTS

The acceptance tests indicated here shall be performed on individual FM CDEs in process or following their assembly, as appropriate and as indicated below. These tests shall be performed at Swales Aerospace or NRL, as indicated below.

Tests are listed below by type. In each section, the test requirements, location of test, and method of reporting are listed following a brief description.

#### 3.1 VISUAL INSPECTION

Each CDE shall be subject to in-process and final visual inspection, as listed here and within the PDA bonding process specification (LAT-PS-01331) and the wrapping and capping process specification.

##### 3.1.1 Requirements

As specified in the PDA bonding procedure (LAT-PS-01331), each PDA optical bond shall be inspected for evidence of delamination, voids, or other significant flaws on the bond edge. This inspection shall be performed as the bond is released from its mold, either approximately 24 hours or approximately 72 hours after it is injected, depending on the stage in the CDE assembly cycle. This inspection may be performed with no magnification or handheld magnification up to x10. Failure to cure, obvious delaminations, presence of 4 or more visible voids, or voids larger than 2 mm shall be grounds for rejection.

As specified in the CDE wrapping and capping procedure (LAT-PS-01332), prior to wrapping, each CDE shall be inspected for significant damage to the crystal volume, chamfers, and bonding faces. This inspection shall be performed with no magnification. Cracks anywhere in the crystal longer than 5 mm and shattered areas on the bonding face larger than 5 mm shall be grounds for rejection. Cracking or shattering damage to the chamfer that extends over more than 20 mm shall be grounds for rejection.

As specified in the CDE wrapping and capping procedure (LAT-PS-01332), after wrapping and capping, each CDE shall be inspected for proper VM2000 wrapper alignment and tightness, wrapper seam sealing tape length, machined end cap tape placement, and end cap seating. These requirements are summarized here.

- The wrapper shall lap over itself on the top face of the crystal, and the overlapped portion of the wrapper shall not be skewed out of alignment by more than 0.7 mm at either end.
- So that the wrapper does not interfere with the placement of the machined end cap, neither end of the wrapper shall extend past the end of the crystal.
- The wrapper seam on the top face of the crystal shall be covered with a 312 mm (+0 mm, -1 mm) strip of 12.7 mm wide Kapton tape. The tape length is chosen so that it does not extend beneath the flange of either end cap, but its ends are covered by end-cap mounting tape.
- The wrapper shall be tight after both ends caps are taped in place.
- The end-cap mounting tape shall not extend onto the chamfers of the end cap. This tape shall cover only the lip of the end cap.
- Both end caps shall be firmly seated onto the crystal end faces such that they do not move when modest finger pressure is applied axially to a corner of the end cap.

Prior to shipping to NRL, each completed CDE lot shall be inspected for quantity and condition.

##### 3.1.2 Test Location

This test shall be performed at Swales. It may be repeated on receipt of CDEs at NRL.

### 3.1.3 Reporting

The date and status of each visual inspection shall be reported on the CDE Traveler. Only CDEs that pass the visual inspections shall be sent to NRL, except as specifically requested otherwise.

Through an NCR, Swales shall notify NRL of crystals with defects that exceed the requirements for rejection. NRL will review each NCR and make a disposition on a case-by-case basis.

## 3.2 MECHANICAL

Each CDE shall have overall dimensions (including bonded PDAs and Optical Reflective Wrap) not to exceed the bounds given in Table 3-1. These critical dimensions are specified in LAT-SS-01133 and repeated in the CDE Assembly Drawing (LAT-DS-01900). The specified dimensions of each CDE shall be inspected with approved and calibrated equipment. The maximum allowable mass of each CDE is 0.80 kg. Each CDE shall be weighed with precision and accuracy not to exceed 1 gram.

### 3.2.1 Requirements

Dimensional and weight requirements are given in the CAL Flight Model Crystal Detector Element Specification, LAT-SS-01133.

The subset of those dimensions to be tested is given in Table 3-1 and is called out in the CDE Assembly Drawing (LAT-DS-1900). The “CDE Total Length” is defined as the distance between the ends of the DPD pin contacts on opposite faces of the crystal, not including the extent of the interconnect wire pairs. The “CDE Cap-to-Cap Length” is defined as the distance between the outer faces of opposite end caps. The “CDE Envelope Height” is defined to be the maximum distance between two planes in contact with the Top and Bottom surfaces of the CDE. The “CDE Envelope Width” is defined to be maximum distance between two planes in contact with the Front and Rear surfaces of the CDE. On a nominal CDE, test planes in contact with the Top, Bottom, Front, and Rear surfaces of the CDE would be in contact with the machined end caps.

The bondline thickness and PDA location on the end faces shall be verified with approved, calibrated equipment.

The minimum and maximum values of the indicated dimensions shall be inspected with approved, calibrated equipment manufactured with tolerances of  $\pm 0.1$  mm or better.

Parameter	Minimum Value (mm)	Maximum Value (mm)
CDE Total Length	NA	336.3
CDE Cap-to-Cap Length	330.8	331.6
CDE Envelope Height	NA	20.4
CDE Envelope Width	NA	27.2
Bondline thickness	0.8	1.0
PDA Height Location	2.40	3.40
PDA Width Location	2.15	3.15
Wrapper Skewness	NA	0.7

Table 3-1. Dimensional requirements for completed CDEs.

The mass of each CDE, including CsI crystal, DPDs, optical bonds, interconnect wire pairs, optical reflective wrap, and machined end caps, shall not exceed 0.80 kg (LAT-SS-01133). The measurement precision and accuracy shall not exceed 1 gram. The average mass of the EM CDEs was 0.782 kg, and the heaviest was 0.789 kg.

### 3.2.2 Test Location

This test shall be performed at Swales.

### 3.2.3 Reporting

The date and status of the dimensional tests and weight measurements shall be reported on the CDE Traveler. The weight measurement shall also be reported on the CDE Tracking Spreadsheet. Only CDEs that pass the mechanical inspections shall be sent to NRL.

## 3.3 OPTICAL

The optical performance of each CDE shall be quantified with the CDE Muon Telescope, the design and use of which is described in LAT-PS-02571. This device records the scintillation light produced by the passage of cosmic ray muons and measured by all four PIN photodiodes of a CDE. The optical properties of 12 CDEs can be measured with the requisite accuracy in a single data run of ~12 hrs. The CDE Muon Telescope will report the following parameters.

- The absolute light yield of all four diodes measured at the center of the CDE.
- The large-to-small diode light yield ratio, PIN B / PIN A for each PDA, measured at the center of the CDE.
- The energy resolution of both large diodes for muons at the center of the CDE.
- The light asymmetry from the large diodes for muons approximately 12 cm on either side of the center of the CDE.
- The light taper of both large diodes for muons approximately 2 cm from each end of the CDE.

### 3.3.1 Requirements

Optical performance requirements are given in the CAL Flight Model Crystal Detector Element Specification, LAT-SS-01133, in which these parameters are defined in some detail. Table 3-2 lists the optical requirements to be tested and the respective maximum and minimum values, as appropriate.

Parameter	Minimum Value	Maximum Value
Light yield, large PIN (e/MeV)	6500	NA
Light yield, small PIN (e/MeV)	1100	NA
Light yield ratio	5	7
Light asymmetry change	0.25	0.70
Light taper	0.45	0.75
End-to-end light yield ratio	0.87	1.15
Muon energy resolution (rms)	NA	8%

Table 3-2. Optical performance requirements.

Similar tests have been performed successfully on EM CDEs.

### 3.3.2 Test Location

This test shall be performed by trained personnel at Swales using the CDE Muon Telescope, which is GFE from NRL. NRL will provide training in the use of the Muon Telescope.

### 3.3.3 Reporting

The CDE Muon Telescope analysis software generates a test report that contains the CDE serial number, the date and test technician's name, and the optical performance values. Optical test reports shall be forwarded to NRL along with the CDE shipments. Only CDEs that meet the optical requirements shall be sent to NRL. CDEs that fail may be reworked or repaired as necessary. Such rework or repair will be conducted under an NCR.

### **3.4 BOND STRENGTH**

One CDE every two weeks of assembly shall be chosen at random and set aside for shear strength testing to destruction. Both PDAs shall be sheared off the crystal using a calibrated load cell, and the PDA displacement and shear-loading data shall be recorded electronically. The shearing load shall be applied uniformly over the full 21 mm × 1.8 mm side surface of the PDA ceramic. The test shall be monitored and witnessed by QA. The shear strength test procedure is given in LAT-PS-02572.

After the shear test, the crystal and sheared PDAs shall be visually inspected and then delivered to NRL with the test report. The crystal may be returned to Swales for reuse.

#### **3.4.1 Requirement**

The shear strength of the PDA bond shall exceed 0.16 N/mm<sup>2</sup>. For the area of the FM optical bond (20.2 mm × 12.4 mm), this corresponds to a shear force of approximately 40 N. For the purpose of this test, this 40 N value shall be defined to be 9 lbf.

Similar tests have been performed on EM CDEs without failures.

#### **3.4.2 Test Location**

This test shall be performed by Swales personnel at NRL or at Swales, according to convenience.

#### **3.4.3 Reporting**

The date, displacement at failure, shear strength at failure, and status of the tests shall be recorded and reported to NRL. Swales shall store the detailed data set of displacement versus shear load electronically, for delivery to NRL on request.

### **3.5 THERMAL STABILITY**

One CDE randomly selected from every two weeks of assembly shall be set aside for thermal stability testing. The optical performance of this CDE (Section 3.3) will be evaluated through 25 thermal cycles at atmospheric pressure in a dry nitrogen purge. The temperature range shall be -30C to +60C, with a ramp rate not to exceed 20C per hour and a soak time of not less than 1 hour. Optical performance measurements shall be made prior to cycling and after 25 cycles. Following the thermal cycling, the machined end caps shall be removed and the PDA bond shall be visually inspected for delamination.

This sample CDE may be the same CDE selected for shear strength testing. In this case, the shear test would occur following thermal cycling. Because this delays the shear test by of order two weeks, we anticipate that the thermal stability test sample and the shear strength test sample will not be the same CDE early in the flight build.

#### **3.5.1 Requirements**

The light yield of each of the four PIN photodiodes shall not decline by more than 20% after thermal cycling relative to its initial value.

There shall be no noticeable physical delamination of either optical bond.

Similar tests have been performed on EM CDEs without failures. Light yields typically decline by ~5% from their initial values.

#### **3.5.2 Test Location**

The thermal cycling shall be performed at NRL, and the muon optical tests will be performed at Swales.

#### **3.5.3 Reporting**

The date, number of thermal cycles, optical performance parameters, and visual inspection shall be reported to NRL. (Environmental records of the thermal cycling shall be reported by NRL to Swales along with the CDE when it is returned to Swales for the post-cycling optical test.)

## 4 ACCEPTANCE DATA PACKAGE

### 4.1 REPORTING

CDEs are assembled in lots of 12. Each lot has associated with it a Swales Traveler that documents the assembly steps and the components used in the assembly. The Traveler shall be made available for review by NRL. Each CDE has a Swales serial number that is [Traveler Number]-[Sequence number], where the Sequence number (1 to 12) is the ordinal number for the bonding sequence within a lot.

Data elements specified in this document shall be reported to NRL in the CDE Tracking Spreadsheet and in the Optical Test Report. The contents of the spreadsheets are specified below. One worksheet within the spreadsheet shall be created for each CDE lot. It shall be transmitted from Swales to NRL via email or on CD with each CDE lot shipment. The spreadsheet shall be created with Microsoft Excel, Office version 2000 or higher.

In addition to the Optical Test Report spreadsheet, the muon optical test also creates an HTML report and data summary plots in PDF format. The optical test data file, HTML report, and data summary plots shall be made available to NRL on request. They may be communicated electronically via email or CD, as appropriate.

#### 4.1.1 Contents of Tracking Spreadsheet

The CDE Tracking Spreadsheet shall contain the serial, batch, and lot numbers of the components of each CDE to establish traceability. In addition, it shall contain the measured mass of the completed CDE and the date of completion of assembly. The completion date may be used to track original and reworked CDEs. The columns of the spreadsheet are listed in Table 4-2. One row of the spreadsheet shall correspond with one CDE.

Column number	Column heading	Description
1	Crystal S/N	Vendor-supplied serial number
2	Left (minus) PDA S/N	Vendor-supplied serial number, left face
3	Right (plus) PDA S/N	Vendor-supplied serial number, right face
4	Wrapper L/N	Vendor-supplied lot number
5	Left (Minus) cap L/N	Vendor-supplied lot number, left face
6	Right (Plus) cap L/N	Vendor-supplied lot number, right face
7	Mass (grams)	Weight of completed CDE, in grams.
8	Swales serial number	Swales serial number for assembled CDE
9	Completion date	Date of completion of assembly of CDE
10	Is Left bond reworked?	
11	Is Right bond reworked?	

Table 4-1: Contents of CDE Tracking Spreadsheet

#### 4.1.2 Contents of Optical Test Report

The CDE Muon Telescope analysis software generates a test report whose contents are summarized below. Tracking Spreadsheet shall contain the serial, batch, and lot numbers of the components of each CDE to establish traceability. In addition, it shall contain the measured mass of the completed CDE and the date of completion of assembly. The completion date may be used to track original and reworked CDEs. The

columns of the spreadsheet are listed in Table 4-2. One row of the spreadsheet shall correspond with one CDE.

Column number	Column heading	Description
1	Crystal S/N	Vendor-supplied serial number
2	Test date	Date of optical test
3	Operator	Name of test technician
4	Data file name	Name of optical test data file from which performance data are derived
5	Light yield, large PIN, Minus face (e/MeV)	
6	Light yield, small PIN, Minus face (e/MeV)	
7	Light yield ratio, large / small, Minus face	
8	Light taper, Minus face (%)	
9	Light yield, large PIN, Plus face (e/MeV)	
10	Light yield, small PIN, Plus face (e/MeV)	
11	Light yield ratio, large / small, Plus face	
12	Light taper, Plus face (%)	
13	End-to-end light yield ratio	
14	Light asymmetry change	
15	Muon resolution (% rms)	

Table 4-2. Contents of CDE muon optical test report.

## 4.2 CERTIFICATE OF CONFORMANCE

Each shipment shall be accompanied by a certificate of conformance with the specified assembly and test procedures. This certification shall be signed by the CDE Project Manager at Swales or his/her designee.